

# Components, Packaging and Manufacturing Technology Society Orange County Chapter

## Presents an All-Day Workshop on **3D Integrated Circuits: Technologies Enabling the Revolution**

Date : **Friday, December 9, 2011**Location: **Jazz Semi Auditorium, [Conexant Systems, Inc. 4321 Jamboree Road, Newport Beach, CA 92660](#)**

### Program Agenda

**09:00 – 09:05am:** Welcome & Introduction**Session – 1: Market, Architecture & Design****09:05 – 09:35am:** *“Opportunities and Challenges for 3D Integrated Heterogeneous Electronic Systems”* – **Prof. Muhannad Bakir, Integrated 3D Systems Group, Georgia Tech, Atlanta, GA****09:35 – 10:05am:** *“Economics to Drive 3D Stacking”* – **Dr. Phil Garrou, Microelectronic Consultants of North Carolina, Research Triangle Park, NC****10:05 – 10:35am:** *“Stack Silicon Interconnect Development and Key Role of Supply Chain Collaboration”* – **Dr. Suresh Ramalingam, Sr. Director, Xilinx, San Jose, CA****10:35 – 10:45am:** Break**10:45 – 11:15am:** *“Emerging Challenges for Power, Signal, and Reliability Verification on 3D-IC/Silicon Interposer Designs”* – **Dr. Norman Chang, Co-Founder, Apache Design Systems, Ansys, San Jose, CA****11:15 – 11:45am:** *“3D IC Test Challenges and Solutions”* – **Dr. Stephen Pateras, Product Marketing Director, Silicon Test, Mentor Graphics, San Jose, CA****11:45 – 12:15pm:** *“<Presentation Title to be announced>”* – **A. La Manna, K. Rebibis, Dr. Eric Beyne, Dr. B. Swinnen, IMEC, Leuven, Belgium****12:15 – 01:15pm:** Lunch**Session – 2: Manufacturing Technologies & Materials****01:15 – 01:45pm:** *“Cost-Effective 3D Semiconductor Packaging Solutions Based on Embedded Die in Laminate Technology”* – **Ted Tessier, Senthil Sivaswamy, Flip Chip International LLC, Phoenix, AZ, Dr. Kazuhisa Itoi, Fujikura Ltd, Tokyo, Japan****01:45 – 02:15pm:** *“Challenges and Solutions in Mid-end and Back-end Processes for 2.5D and 3D TSV – an OSAT Perspective”* – **Dr. Yeong Lee, Product and Tech. Marketing Director, STATS ChipPAC, Fremont, CA****02:15 – 02:45pm:** *“Advanced Underfills for 2.5D and 3D Applications”* – **Dr. Rose Guino, Dr. Betty Huang, Dr. Kevin Becker, Dr. T. Takano, Henkel Electronic Materials, LLC, Irvine, CA****02:45 – 03:00pm:** Break**03:00 – 03:30pm:** *“3D TSV Interposer and its Applications”* – **Dr. GS Kim, Founder & CEO, EPWorks, Ltd. Seoul, Korea****03:30 – 04:00pm:** *“Via Reveal – High rate Si Thinning and Low Temperature Dielectrics for Post-TSV Processing”* – **David Butler, Vice President – Marketing, SPTS Technologies, Newport, UK****04:00 – 04:05pm:** Vote of Thanks**Registrations:**

Early-Bird Registration Fees: IEEE Members - \$40; Non-Members of IEEE - \$50; Students - \$20 (includes lunch &amp; parking)

Prices will go up by \$20 for each category, after November 25, 2011.

Registration Instructions at [http://meetings.vtools.ieee.org/meeting\\_view/list\\_meeting/8019](http://meetings.vtools.ieee.org/meeting_view/list_meeting/8019)**Platinum Sponsors****Gold Sponsors****Workshop Organizing Committee****General Chair**Dr. Lawrence Williams, ANSYS Corporation, [lwilliams@ieee.org](mailto:lwilliams@ieee.org)**Technical Program**Dr. Donald Frye, Henkel Electronics Materials LLC, [don3569@yahoo.com](mailto:don3569@yahoo.com)Robert Warren, Conexant Systems, Inc. [Robert.Warren@conexant.com](mailto:Robert.Warren@conexant.com)Sam Karikalan, Broadcom Corporation, [samkarikalan@ieee.org](mailto:samkarikalan@ieee.org)**Vendor Exhibits:**Mark Kuhlman, Semtech Corporation, [mkuhlman@semtech.com](mailto:mkuhlman@semtech.com)**Publicity & Local Arrangements:**Jaydutt Joshi, Skyworks Solutions, Inc., [jaydutt@gmail.com](mailto:jaydutt@gmail.com)Aaron Edwards, ANSYS Corporation, [aaron.edwards@ansys.com](mailto:aaron.edwards@ansys.com)**University Relations:**Prof. Mark Bachman, Univ. of California – Irvine, [mbachman@uci.edu](mailto:mbachman@uci.edu)**Registration & Finances:**Melissa Lau, Broadcom Corporation, [melissa@broadcom.com](mailto:melissa@broadcom.com)**Vendor  
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